

半田×接着剤の複合材料 半田接続と樹脂補強を一括形成!

Solder x Adhesive Composite material
Solder connection and resin reinforcement are collectively formed!



半田粒子集合型異方導電性接着剤

Self-assembly Anisotropic Conductive Adhesive

特長 Features

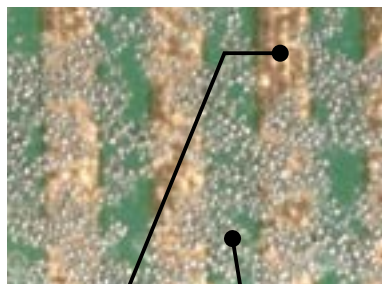
- **Mini-LEDを実装可能**
Mini-LED can be mounted
- **接続信頼性良好**
Good connection reliability
- **低温実装**
Low temperature mounting (180deg.C)
- **窒素雰囲気不要**
N₂ atmosphere unnecessary

特性 Properties

半田粒子が電極に集合

Solder particles gather on the electrode by heating

[Before heating]



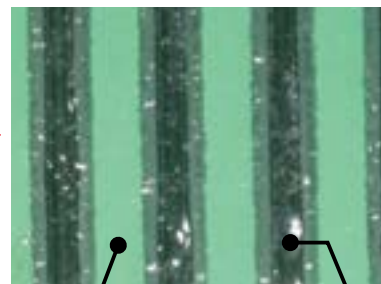
Substrate :
FR-4

Electrode :
Cu / Au plating

Solder particles

180°C

[After heating]



Space :
Cured adhesive resin

Solder self-assembles on
electrodes

用途 Application

- **Mini-LED実装**
Mini-LED mounting material

